



Modsemi ECC CryptoAuthentication Secure Elements

Revision history

Document version	Date of release	Description of changes
1.32	2022-03-05	Add Part numbering
1.31	2022-02-01	
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1.00	2019-05-01	Initial Version
0.51	2017-03-19	Draft Version
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Modsemi ECC CryptoAuthentication Secure Elements

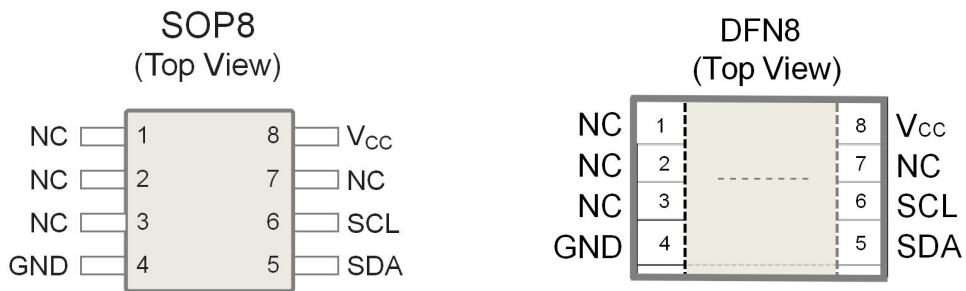
Key features

- Security co-processor with cryptographic algorithm and key storage
 - > High-end security controller
 - > Protected Storage for Keys, Certificates or Data
- Hardware Support for Asymmetric Sign, Verify, authentication, Key Agreement:
 - > Hardware cryptographic algorithm processor: SM2, ECC-P256, SHA-256, TRNG
 - > ECDSA: Elliptic Curve Digital Signature
 - > ECDH: Elliptic Curve Diffie-Hellman
 - > SM2: Diffie-Hellman Ephemeral (ECDHE) over the SM2 elliptic curve
- Hardware Support for Symmetric Algorithms:
 - > SHA-256 & HMAC
 - > SM4: Block-cipher symmetric algorithm Encrypt/Decrypt
 - > AES-128/256: Encrypt/Decrypt
- Networking Key Management Support:
 - > security key generation and key agreement
 - > Communication data encryption with protected
 - > Turnkey PRF/HKDF calculation for TLS
- Security update and firmware Support:
 - > High security ECDSA firmware signature validation
 - > Full life cycle secure boot validation
 - > Firmware upgrade protection and data encryption protection
- Internal High-Quality NIST Standard Random Number Generator (RNG)
- Up to 5kB of user security storage to store extended security information
- Unique Serial Number
- High-Endurance Monotonic Counters
- Interface Options Available 400k/1 MHz Standard I2C Interface
- Fast and easy integration
- DFN8 and SOP8 Packages

Benefits

- IoT network endpoint key management & exchange/IoT Node Crypto-Protection
- Encryption protection and key protection of IoT nodes
- Protect the authenticity, integrity and confidentiality of your products, data and intellectual property
- Secure communication and communication data encryption
- Data storage protection
- Lifecycle management
- Platform integrity protection
- Security update and firmware protection
- Electronic accessories protection

Description of PIN



Pin	Function
GND	Ground
SDA	Serial Data
SCL	Serial Clock Input
V _{CC}	Power Supply
NC	No Connect

Table of Contents

Intended audience

This Datasheet is intended for device integrators and board manufacturers.

Key features.....	2
Benefits.....	2
Description of PIN.....	2
1. Introduction.....	4
1.1 Introduction.....	4
1.2 Features.....	4
2. Interface and Schematics.....	5
2.1 System Integration Schematics.....	5
3. Electrical Characteristics.....	5
3.1 Absolute Maximum Ratings.....	5
3.2 Reliability.....	6
3.3 DC Parameters: All I/O Interfaces.....	6
4. Package Drawings.....	7
4.1 DFN8.....	8

1. Introduction

1.1 Introduction

The MOD8ID is a high-security authenticator that provides a core set of cryptographic accelerators derived from integrated asymmetric (ECC-P256/SM2) and symmetric (SHA-256/AES/SM4) security functions. In addition to the security services provided by the hardware implemented crypto engines, the device integrates a FIPS/NIST true random number generator (RNG), 5Kb of secured NVM, a decrement-only counter, The MOD8ID combine key storage with advanced hardware cryptographic accelerators to implement various authentication applications.

1.2 Features

The MOD8ID based on an advanced security controller with built-in tamper proof NVM for secure storage and Symmetric/Asymmetric crypto engines to support SM2, SM4, ECC 256 and AES/SHA-256. The MOD8ID includes an security NVM which can be used for storage keys, certificates and private data, security read/write, read-only or secret data, consumption logging, and security configurations. This new security technology greatly enhances your overall system security.

MOD8ID has an I2C interface that supports secure communication, which can easily and fast integrate with host microcontroller software.

MOD8ID covers a broad range of use cases necessary for many types of security applications that include the following:

- > IoT node/edge computing node equipment
- > Smart home
- > Electronic Accessories
- > Mobile devices
- > Webcam
- > smart Lock

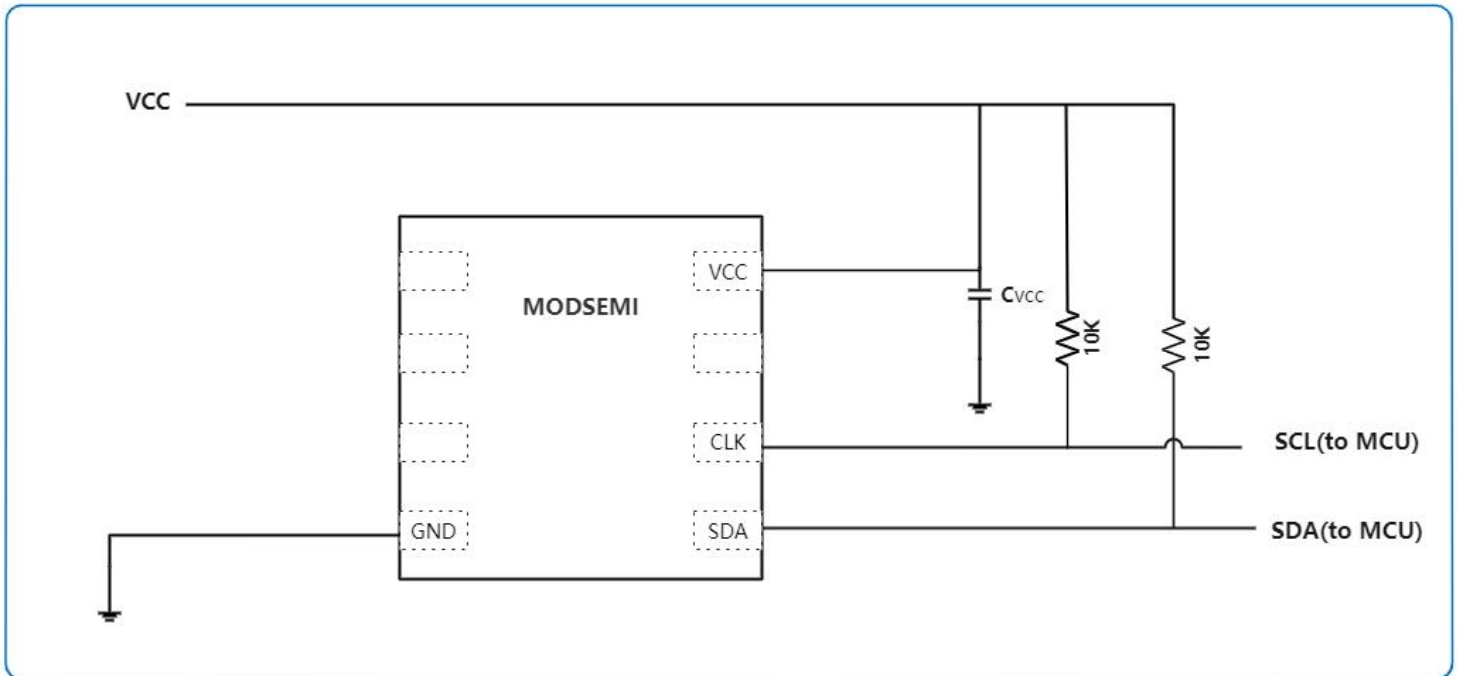
2. Interface and Schematics

This section explains the schematics of the product and gives some recommendations as to how the controller should be externally connected.

2.1 System Integration Schematics

The following figure illustrates how to integrate MOD8ID with your local host.

Figure 2 -1 System Integration Schematic Diagram



Note: Value of the pull up resistors and C_{vcc} depend on the target application circuit and the targeted I2C frequency.

3. Electrical Characteristics

3.1 Absolute Maximum Ratings

Parameter	Description	Min.	Max.	Units
TS	Storage Temperature	-55	125	°C
TA	Operating Temperature	-40	85	°C
VCC	Operating Voltage	1.62	3.3	V
VESD	Human Body Model(HBM) ESD	-	4000	V

Note: Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification are not implied. Exposure to absolute

maximum rating conditions for extended periods may affect device reliability.

3.2 Reliability

The MOD8ID is fabricated with high reliability NVM manufacturing technology.

Table 3-1. FLASH Reliability

Parameter	Min.	Typ.	Max.	Units
Write Endurance	100,000	—	—	Write Cycles
Data Retention	10	—	—	Years
Read Endurance	Unlimited			Read Cycles

3.3 DC Parameters: All I/O Interfaces

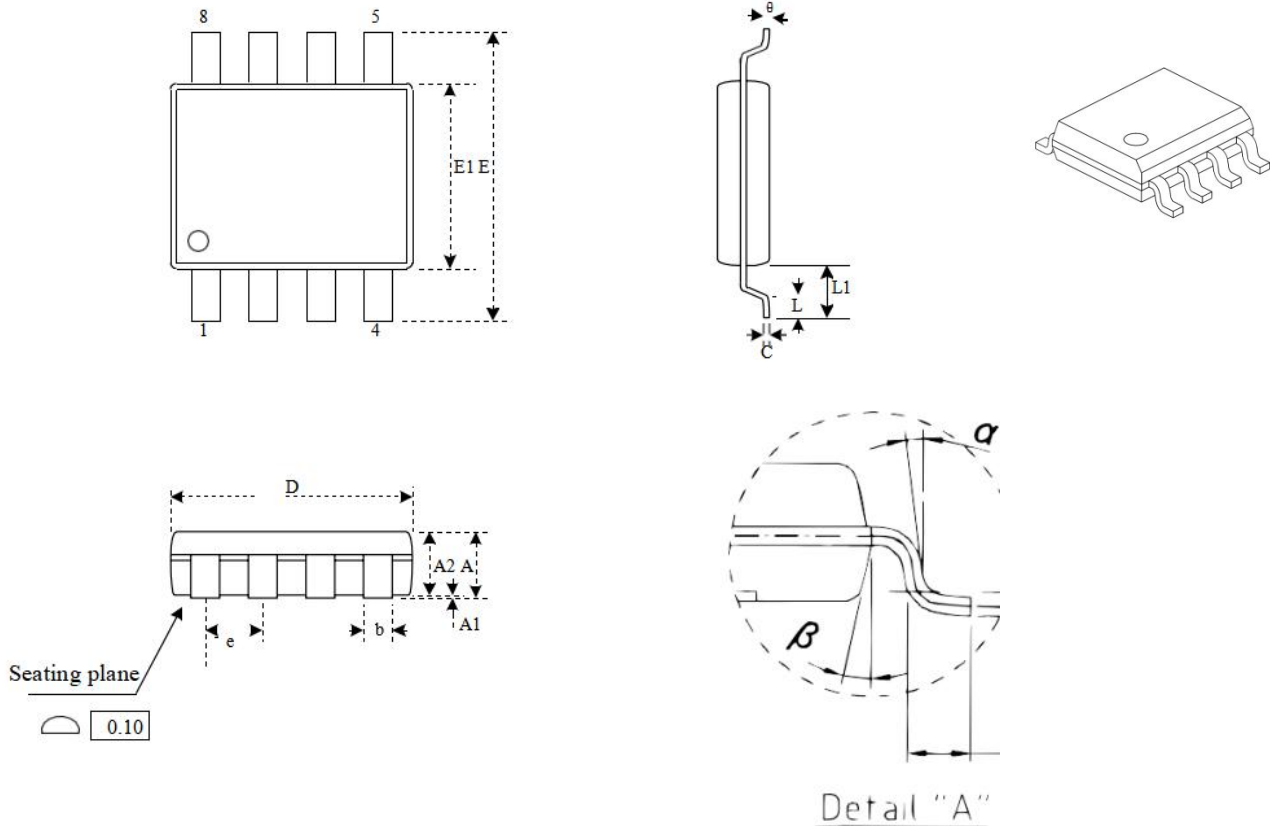
Table 3-2 DC Parameters on All I/O Interfaces

参数	条件	VCC	Min	Type	Max	单位
VIH	Input high voltage, all standard inputs and bidirectional ports	3.3V	2.0	-	-	V
		1.8V	1.2	-	-	V
VIL	Input low voltage, all standard inputs and bidirectional ports	3.3V	-	-	0.8	V
		1.8V	-	-	0.6	V
VOH	All standard inputs and bidirectional ports	3.3V	VCC-0.4	-	-	V
		1.8V	VCC-0.4	-	-	V
VOL	Output low voltage, all standard inputs and two-way ports	3.3V	-	-	0.4	V
		1.8V	-	-	0.4	V
IIL	IO pad force -0.2V @VDDIO=3.6V, IIL= -120~-70uA					
IIH	IO pad force 3.8V @VDDIO=3.6V, IIH = 8uA~16uA					
Icc	Waiting for I/O during I/O transfers or execution of non-ECC/SM2 commands. Independent of Clock Divider value.	3.3V	-	1.6	-	mA

4. Package Drawings

4.1 SOP8

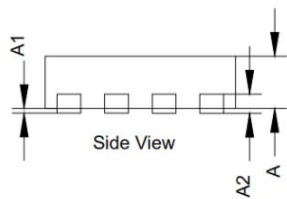
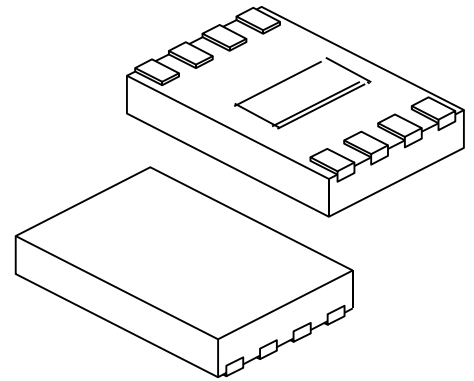
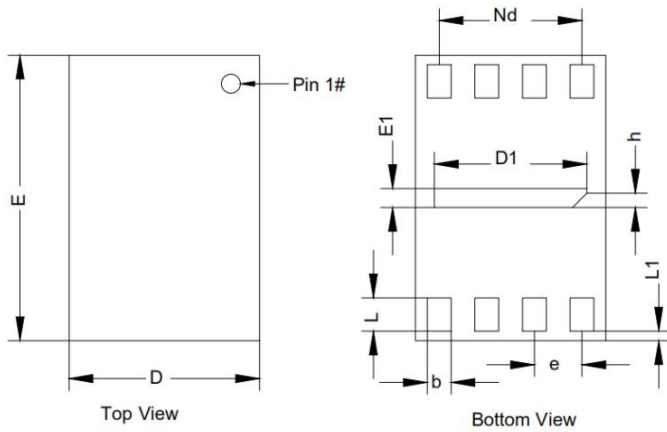
Narrow, 3.90 mm (.150 In.) Body [SOP8]



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETERS)															
Symbol	A	A1	A2	b	C	D	E	E1	e	L	L1	θ	α	β	
Unit															
mm	Min	1.35	0.05	1.35	0.31	0.15	4.77	5.80	-	-	0.40	0.85	0°	6°	11°
	Nom	-	-	-	-	-	4.90	6.00	3.90	1.27	-	1.06	-	7°	12°
	Max	1.75	0.25	1.55	0.51	0.25	5.03	6.20	-	-	0.90	1.27	8°	8°	13°
Inch	Min	0.053	0.002	0.053	0.012	0.006	0.188	0.228	-	-	0.016	0.033	0°	6°	11°
	Nom	-	-	-	0.016	-	0.193	0.236	0.154	0.050	-	0.042	-	7°	12°
	Max	0.069	0.010	0.061	0.020	0.010	0.198	0.244	-	-	0.035	0.050	8°	8°	13°

4.2 DFN8

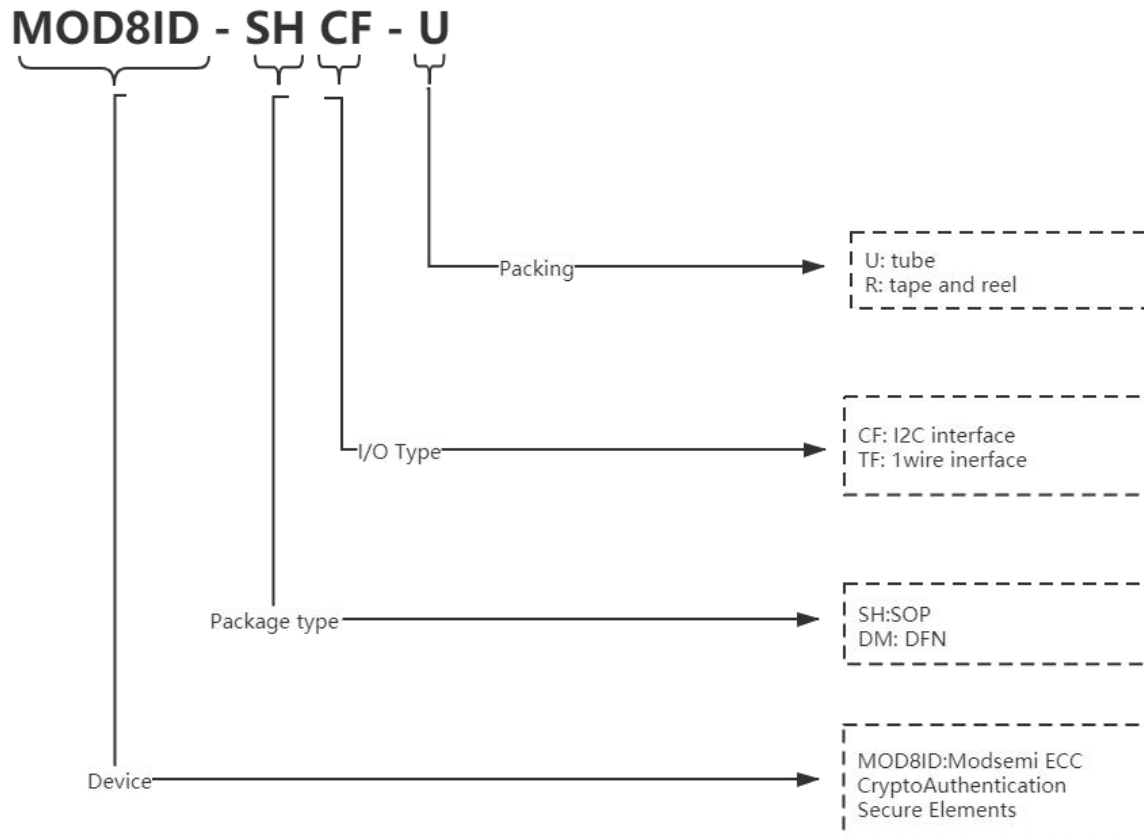
2x3mm body [DFN8]



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETERS)			
SYMBOL	MILLIMETERS		
	MIN	NOM	MAX
A	0.50	0.55	0.60
A1	0.00	0.02	0.05
A2	0.152REF		
b	0.20	0.25	0.30
D	1.95	2.00	2.05
E	2.95	3.00	3.05
D1	1.50	1.60	1.70
E1	0.10	0.20	0.30
e	0.50BSC		
Nd	1.50BSC		
L	0.30	0.35	0.40
L1	0.05	0.10	0.15
h	0.10	0.15	0.20

5. Part numbering

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Examples:

- **MOD8ID-SHCF-U**: SOP8 (0.150" Wide Body), I²C, Tube
- **MOD8ID-DMCF-R**: DFN(2 x 3 x 0.6 mm Body), I²C, Type and Reel



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